Ultra-Low Power, AT Command / API Controlled, Sigfox[®] Compliant Transceiver IC for Up-Link and Down-Link



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OVERVIEW

Circuit Description

AX-SFEU and AX-SFEU-API are ultra-low power single chip solutions for a node on the Sigfox network with both up- and down-link functionality. The AX-SFEU chip is delivered fully ready for operation and contains all the necessary firmware to transmit and receive data from the Sigfox network in Europe. It connects to the customer product using a logic level RS232 UART. AT commands are used to send frames and configure radio parameters.

The AX-SFEU-API variant is intended for customers wishing to write their own application software based on the AX-SF-LIB-1-GEVK library.

Features

Functionality and Ecosystem

- Sigfox up-link and down-link functionality controlled by AT commands or API
- The AX-SFEU and AX-SF-API ICs are part of a whole development and product ecosystem available from ON Semiconductor for any Sigfox requirement. Other parts of the ecosystem include
 - Ready to go development kit DVK-SFEU-[API]-1-GEVK including a 2 year Sigfox subscription
 - Sigfox Ready[®] certified reference design for the AX-SFEU and AX-SFEU-API ICs
 - AX-SF10-MINI21-868-B1 and AX-SF10-ANT21-868-B1, Sigfox compliant SMT modules based on AX-SFEU with 50 Ω pads or chip antenna. Not available for AX-SFEU-API

General Features

- QFN40 5 mm x 7 mm package
- Supply range 2.1 3.6 V
- -40° C to 85° C
- Temperature sensor
- Supply voltage measurements

• 10 GPIO pins

- ◆ 4 GPIO pins with selectable voltage measure functionality, differential (1 V or 10 V range) or single ended (1 V range) with 10 bit resolution
- 2 GPIO pins with selectable sigma delta DAC output functionality
- 2 GPIO pins with selectable output clock
- 3 GPIO pins selectable as SPI master interface
- Integrated RX/TX switching with differential antenna pins

Power Consumption

- Ultra-low Power Consumption:
 - ◆ Charge required to send a Sigfox OOB packet at 14 dBm output power: 0.28 C
 - Deep Sleep mode current: 100 nA
 - Sleep mode current: 1.3 μA
 - Standby mode current: 0.5 mA
 - ◆ Continuous radio RX-mode at 869.525 MHz : 10 mA
 - ◆ Continuous radio TX-mode at 868.130 MHz
 19 mA @ 0 dBm
 49 mA @ 14 dBm

High Performance Narrow-band Sigfox RF Transceiver

- Receiver
 - ◆ Carrier frequency 869.525 MHz
 - ♦ Data-rate 600 bps FSK
 - Sensitivity
 - -126 dBm @ 600 bps, 869.525 MHz, GFSK
 - 0 dBm maximum input power
- Transmitter
 - Carrier frequency 868.13 MHz
 - ◆ Data-rate 100 bps PSK
 - High efficiency, high linearity integrated power amplifier
 - Maximum output power 14 dBm
 - Power level programmable in 1 dBm steps

Applications

1

Sigfox networks up-link and down-link.

BLOCK DIAGRAM

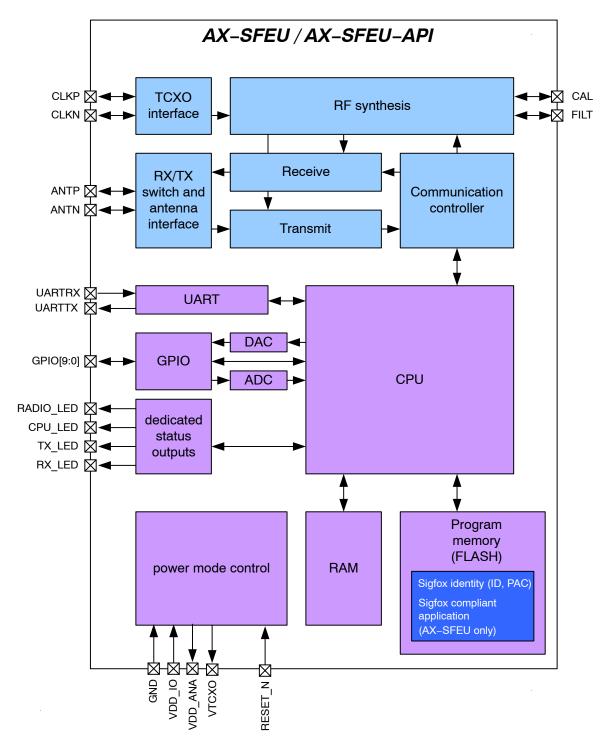


Figure 1. Functional Block Diagram of the AX-SFEU / AX-SFEU-API

Table 1. PIN FUNCTION DESCRIPTIONS

| Symbol | Pin(s) | Type | Description |
|--------------------|--------|----------|---|
| VDD_ANA | 1 | Р | Analog power output, decouple to neighboring GND |
| GND | 2 | Р | Ground, decouple to neighboring VDD_ANA |
| ANTP | 3 | Α | Differential antenna input/output |
| ANTN | 4 | А | Differential antenna input/output |
| NC | 5 | N | Do not connect |
| GND | 6 | Р | Ground, decouple to neighboring VDD_ANA |
| VDD_ANA | 7 | Р | Analog power output, decouple to neighboring GND |
| GND | 8 | Р | Ground |
| FILT | 9 | Α | Synthesizer filter |
| L2 | 10 | Α | Must be connected to pin L1 |
| L1 | 11 | Α | Must be connected to pin L2 |
| NC | 12 | N | Do not connect |
| GPIO8 | 13 | I/O/PU | General purpose IO |
| GPIO7 | 14 | I/O/PU | General purpose IO, selectable SPI functionality (MISO) |
| GPIO6 | 15 | I/O/PU | General purpose IO, selectable SPI functionality (MOSI) |
| GPIO5 | 16 | I/O/PU | General purpose IO, selectable SPI functionality (SCK) |
| GPIO4 | 17 | I/O/PU | General purpose IO, selectable $\Sigma\Delta$ DAC functionality, selectable clock functionality |
| CPU_LED | 18 | 0 | CPU activity indicator |
| RADIO_LED | 19 | 0 | Radio activity indicator |
| VTCXO | 20 | 0 | TCXO power |
| GPIO9 | 21 | I/O/PU | General purpose IO, wakeup from deep sleep |
| UARTTX | 22 | 0 | UART transmit |
| UARTRX | 23 | I/PU | UART receive |
| RXLED/ DBG_DATA | 24 | O I/O | Receive activity indicator in AX–SFEU Debugger data line in AX–SFEU–API |
| TXLED/ DBG_CLK | 25 | 0 | Transmit activity indicator in AX-SFEU Debugger clock line in AX-SFEU-API |
| NC/ DBG_EN | 26 | PD PD | Do not connect in AX-SFEU Debugger enable line in AX-SFEU-API |
| RESET_N | 27 | I/PU | Optional reset pin. Internal pull-up resistor is permanently enabled, nevertheles it is recommended to connect this pin to VDD_IO if it is not used |
| GND | 28 | Р | Ground |
| VDD_IO | 29 | Р | Unregulated power supply |
| GPIO0 | 30 | I/O/A/PU | General purpose IO, selectable ADC functionality, selectable $\Sigma\Delta$ DAC functionality, selectable clock functionality |
| GPIO1 | 31 | I/O/A/PU | General purpose IO, selectable ADC functionality |
| GPIO2 | 32 | I/O/A/PU | General purpose IO, selectable ADC functionality |
| NC | 33 | N | Do not connect |
| NC | 34 | N | Do not connect |
| GPIO3 | 35 | I/O/A/PU | General purpose IO, selectable ADC functionality |
| VDD_IO | 36 | Р | Unregulated power supply |
| CAL | 37 | Α | Connect to FILT as shown in the application diagram |
| NC | 38 | N | Do not connect |

Table 1. PIN FUNCTION DESCRIPTIONS

| Symbol | Pin(s) | Туре | Description | |
|--------|------------|------|--|--|
| CLKN | 39 | Α | TCXO interface | |
| CLKP | 40 | Α | TCXO interface | |
| GND | Center pad | Р | Ground on center pad of QFN, must be connected | |

A = analog

I = digital input signal

O = digital output signal

PU = pull-up

I/O = digital input/output signal

N = not to be connected

P = power or ground

PD = pull-down

All digital inputs are Schmitt trigger inputs, digital input and output levels are LVCMOS/LVTTL compatible. Pins GPIO[3:0] must not be driven above VDD IO, all other digital inputs are 5 V tolerant. All GPIO pins and UARTRX start up as input with pull-up. For explanations on how to use the GPIO pins, see chapter "AT Commands".

Table 2.

| Pin | Possible GPIO Modes |
|-------|---------------------|
| GPIO0 | 0, 1, Z, U, A, T |
| GPIO1 | 0, 1, Z, U, A |
| GPIO2 | 0, 1, Z, U, A |
| GPIO3 | 0, 1, Z, U, A |
| GPIO4 | 0, 1, Z, U, T |
| GPIO5 | 0, 1, Z, U |
| GPIO6 | 0, 1, Z, U |
| GPI07 | 0, 1, Z, U |
| GPIO8 | 0, 1, Z, U |
| GPIO9 | 0, 1, Z, U |

0 = pin drives low

1 = pin drives high

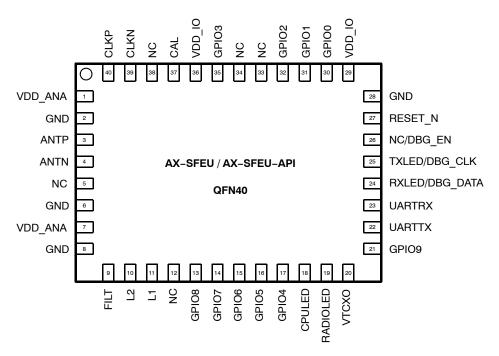
A = pin is analog input

T = pin is driven by clock or DAC

U = pin is input with pull-up

Z = pin is high impedance input

Pinout Drawing



NOTE: Pins 24-26 have different functionalities in AT command and API versions, so for these pins AX-SFEU/AX-SFEU-API explanations are shown respectively.

Figure 2. Pinout Drawing (Top View)

SPECIFICATIONS

Table 3. ABSOLUTE MAXIMUM RATINGS

| Symbol | Description | Condition | Min | Max | Units |
|------------------|--|-------------------------------|-------|------|-------|
| VDD_IO | Supply voltage | | -0.5 | 5.5 | ٧ |
| IDD | Supply current | | | 200 | mA |
| P _{tot} | Total power consumption | | | 800 | mW |
| P _i | Absolute maximum input power at receiver input | ANTP and ANTN pins in RX mode | | 10 | dBm |
| I _{I1} | DC current into any pin except ANTP, ANTN | | -10 | 10 | mA |
| I _{I2} | DC current into pins ANTP, ANTN | | -100 | 100 | mA |
| Io | Output Current | | | 40 | mA |
| V _{ia} | Input voltage ANTP, ANTN pins | | -0.5 | 5.5 | V |
| | Input voltage digital pins | | -0.5 | 5.5 | V |
| V _{es} | Electrostatic handling | HBM | -2000 | 2000 | ٧ |
| T _{amb} | Operating temperature | | -40 | 85 | °C |
| T _{stg} | Storage temperature | | -65 | 150 | °C |
| Tj | Junction Temperature | | | 150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

Table 4. SUPPLIES

Conditions for all current and charge values unless otherwise specified are for the hardware configuration described in the AX-SFEU Application Note: Sigfox Compliant Reference Design.

| Symbol | Description | Condition | Min | Тур | Max | Units |
|---------------------------|--|---------------------------------------|-----|------|-----|-------|
| T _{AMB} | Operational ambient temperature | | -40 | 27 | 85 | °C |
| VDD _{IO} | I/O and voltage regulator supply voltage | | 2.1 | 3.0 | 3.6 | V |
| VDD _{IO_R1} | I/O voltage ramp for reset activation | Ramp starts at VDD_IO ≤ 0.1 V | 0.1 | | | V/ms |
| VDD _{IO_R2} | I/O voltage ramp for reset activation | Ramp starts at 0.1 V < VDD_IO < 0.7 V | 3.3 | | | V/ms |
| I _{DS} | Deep sleep mode current | AT\$P=2 | | 100 | | nA |
| I _{SLP} | Sleep mode current | AT\$P=1 | | 1.3 | | μΑ |
| I _{STDBY} | Standby mode current Note 2 | | | 0.5 | | mA |
| I _{RX_CONT} | Current consumption continuous RX | AT\$SE | | 10 | | mA |
| Q _{SFX_OOB_0} | Charge to send a Sigfox out of band message, 0 dBm | AT\$S0 | | 0.12 | | С |
| Q _{SFX_BIT_0} | Charge to send a bit, 0 dBm | AT\$SB=0 | | 0.08 | | С |
| Q _{SFX_BITDL_0} | Charge to send a bit with downlink receive, 0 dBm | AT\$SB=0,1 | | 0.27 | | С |
| Q _{SFX_LFR_0} | Charge to send the longest possible Sigfox frame (12 byte) , 0dBm | AT\$SF=00112233445566778899aabb | | 0.14 | | С |
| Q _{SFX_LFRDL_0} | Charge to send the longest possible Sigfox frame (12 byte) with downlink receive, 0 dBm | AT\$SF=00112233445566778899aabb,1 | | 0.27 | | С |
| Q _{SFX_OOB_14} | Charge to send a Sigfox out of band message, 14 dBm | AT\$S0 | | 0.28 | | С |
| Q _{SFX_BIT_14} | Charge to send a bit, 14 dBm | AT\$SB=0 | | 0.20 | | С |
| Q _{SFX_BITDL_14} | Charge to send a bit with downlink receive, 14 dBm | AT\$SB=0,1 | | 0.35 | | С |
| Q _{SFX_LFR_14} | Charge to send the longest possible Sigfox frame (12 byte) , 14 dBm | AT\$SF=00112233445566778899aabb | | 0.39 | | С |
| Q _{SFX_LFRDL_14} | Charge to send the longest possible Sigfox frame (12 byte) with downlink receive, 14 dBm | AT\$SF=00112233445566778899aabb,1 | | 0.46 | | С |
| I _{TXMOD0AVG} | Modulated Transmitter Current, Note 1 | Pout=0 dBm; average | | 19.0 | | mA |
| I _{TXMOD14AVG} | Modulated Transmitter Current, Note 1 | Pout=14 dBm; average | | 49.0 | | mA |

^{1.} The output power of the AX-SFEU / AX-SFEU-API can be programmed in 1 dB steps from 0 dBm - 14 dBm. Current consumption values are given for a matching network that is optimized for 14 dBm output. 0 dBm transmission with typically 10 mA can be achieved with other networks that are optimized for 0 dBm operation.

^{2.} Internal 20 MHz oscillator, voltage conditioning and supervisory circuit running.

Typical Current Waveform

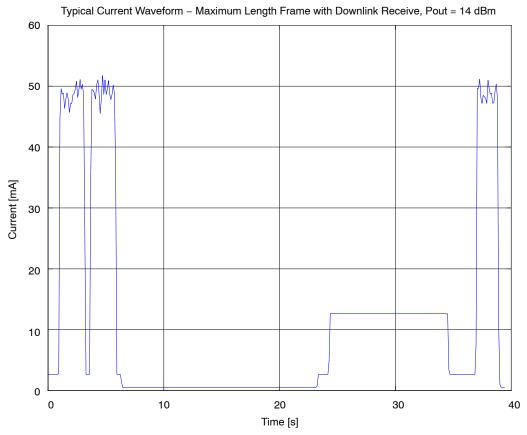


Figure 3. Typical Current Waveform for a Maximum Length Frame with Downlink Receive at 14 dBm Output Power

Battery Life Examples

Scenario 1:

- CR2032 coin cell battery
- One OOB frame transmitter per day at Pout=0 dBm
- Device in Sleep
- Neglecting battery self discharge

| CR2032 capacity | 225 mAh * 3600 s/h | 810 C |
|--------------------------|--------------------|------------|
| Sleep charge per day | 1.3 μA * 86400 s | 0.11 C/day |
| OOB frame transmission | | 0.12 C/day |
| Total Charge consumption | | 0.23 C/day |
| Battery life | | 9.6 Years |

Scenario 2:

- 2 AAA Alkaline batteries in series
- One OOB frame transmitter per day at Pout=14 dBm
- Four maximum length frames with downlink receive per day at Pout=14 dBm
- Device in Sleep
- Neglecting battery self discharge

| 2 AAA alkaline capacity | 1500 mAh * 3600 s/h | 5400 C |
|----------------------------------|---------------------|------------|
| Sleep charge per day | 1.3 μA * 86400 s | 0.11 C/day |
| OOB frame transmission | | 0.28 C/day |
| Frame transmission with downlink | 4 * 0.46 C/day | 1.84 C/day |
| Total Charge consumption | | 2.26 C/day |
| Battery life | | 6.5 Years |

Table 5. LOGIC

| Symbol | Description | Condition | Min | Тур | Max | Units |
|-----------------|---|-------------------------|------|------|--------|-------|
| Digital Inpu | ts | | • | | 1 | |
| V_{T+} | Schmitt trigger low to high threshold point | VDD_IO = 3.3 V | | 1.55 | | V |
| V_{T-} | Schmitt trigger high to low threshold point | 1 | | 1.25 | | V |
| V _{IL} | Input voltage, low | 1 | | | 0.8 | V |
| V_{IH} | Input voltage, high | 1 | 2.0 | | | V |
| V_{IPA} | Input voltage range, GPIO[3:0] | | -0.5 | | VDD_IO | V |
| V_{IPBC} | Input voltage range, GPIO[9:4], UARTRX | | -0.5 | | 5.5 | V |
| IL | Input leakage current | | -10 | | 10 | μΑ |
| R_{PU} | Programmable Pull-Up Resistance | | | 65 | | kΩ |
| Digital Outp | puts | | | | | |
| I _{OH} | Output Current, high Ports GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED | V _{OH} = 2.4 V | 8 | | | mA |
| l _{OL} | Output Current, low GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED | V _{OL} = 0.4 V | 8 | | | mA |
| I _{OZ} | Tri-state output leakage current | | -10 | | 10 | μА |

AC Characteristics

Table 6. TCXO REFERENCE INPUT

| Symbol | Description | Condition | Min | Тур | Max | Units |
|-------------------|----------------|---|-----|-----|-----|-------|
| f _{TCXO} | TCXO frequency | A passive network between the TCXO output and the pins CLKP and CLKN is required. | | 48 | | MHz |
| | | For detailed TCXO network recommendations depending on the TCXO output swing refer to the AX5043 Application Note: Use with a TCXO Reference Clock. | | | | |
| | | For TCXO recommendations see the Ax– SFEU Application Note: Sigfox Compliant Ref- erence Design | | | | |

Table 7. TRANSMITTER

Conditions for transmitter specifications unless otherwise specified with the antenna network from AX-SFEU Application Note: Sigfox Compliant Reference Design and at 868.130 MHz.

| Symbol | Description | Condition | Min | Тур | Max | Units |
|----------------------|---|-----------------------|-----|------|-----|-------|
| SBR | Signal bit rate | | | 100 | | bps |
| PTX _{min} | Lowest Transmitter output power | AT\$CW=868130000,1,0 | | 0 | | dBm |
| PTX _{max} | Highest Transmitter output power | AT\$CW=868130000,1,14 | | 14 | | dBm |
| PTX _{step} | Programming step size output power | | | 1 | | dB |
| dTX _{temp} | Transmitter power variation vs. temperature | -40°C to +85°C | | ±0.5 | | dB |
| dTX _{Vdd} | Transmitter power variation vs. VDD_IO | 1.9 to 3.6 V | | ±0.5 | | dB |
| PTX _{harm2} | Emission @ 2 nd harmonic | | | -51 | | dBc |
| PTX _{harm3} | Emission @ 3 rd harmonic | | | -63 | | |
| PTX _{harm4} | Emission @ 4 th harmonic | | | -84 | | |

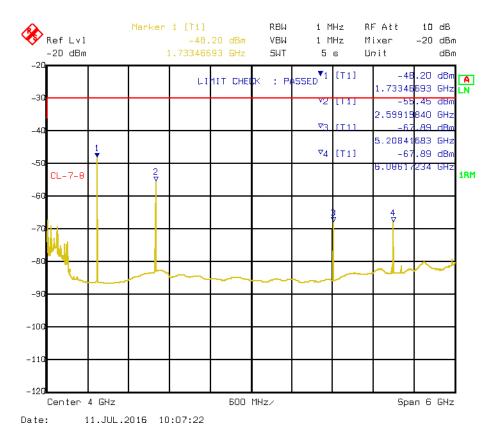


Figure 4. Typical Spectrum with Harmonics at 14 dBm Output Power

Table 8. RECEIVER

Conditions for receiver specifications unless otherwise specified with the antenna network from AX-SFEU Application Note: Sigfox Compliant Reference Design and at 869.525 MHz.

| Symbol | Description | Condition | Min | Тур | Max | Units |
|------------------------|--------------------------------|---|-----|------|-----|-------|
| SBR | Signal bit rate | | | 600 | | bps |
| IS _{BER868} | | AT\$SPN=4,n, BER < 10 ⁻³ | | -126 | | dBm |
| BLK _{2M_868} | Blocking at ±2 MHz off- set | Channel/Blocker @ PER = 0.1, wanted signal level is +3 dB above the typical sensitivity, the blocker signal is CW | | 68 | | dB |
| BLK _{10M_868} | Blocking at ±10 MHz offset | Channel/Blocker @ PER = 0.1, wanted signal level is +3 dB above the typical sensitivity, the blocker signal is CW | | 78 | | dB |

Table 9. ADC / TEMPERATURE SENSOR

| Symbol | Description | Condition | Min | Тур | Max | Units |
|------------------------|--|-----------|------|-----|--------|-------|
| ADCRES | ADC resolution | | | 10 | | Bits |
| V _{ADCREF} | ADC reference voltage | | 0.95 | 1 | 1.05 | V |
| Z _{ADC00} | Input capacitance | | | | 2.5 | pF |
| DNL | Differential nonlinearity | | | ± 1 | | LSB |
| INL | Integral nonlinearity | | | ± 1 | | LSB |
| OFF | Offset | | | 3 | | LSB |
| GAIN_ERR | Gain error | | | 0.8 | | % |
| ADC in Differ | ential Mode | • | | | | |
| V _{ABS_DIFF} | Absolute voltages & common mode voltage in differential mode at each input | | 0 | | VDD_IO | V |
| V _{FS_DIFF01} | Full swing input for differential signals | Gain x1 | -500 | | 500 | mV |
| V _{FS_DIFF10} | | Gain x10 | -50 | | 50 | mV |
| ADC in Single | e Ended Mode | • | • | | • | • |
| V _{MID_SE} | Mid code input voltage in single ended mode | | | 0.5 | | V |
| V _{IN_SE00} | Input voltage in single ended mode | | 0 | | VDD_IO | V |
| V _{FS_SE01} | Full swing input for single ended signals | Gain x1 | 0 | | 1 | V |
| Temperature | Sensor | | • | | • | • |
| T _{RNG} | Temperature range | AT\$T? | -40 | | 85 | °C |
| T _{ERR_CAL} | Temperature error | AT\$T? | -2 | | 2 | °C |

COMMAND INTERFACE

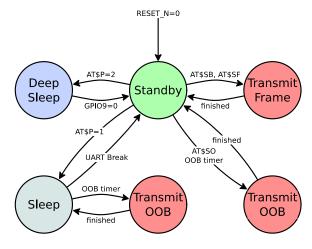
General Information

The chapter "Command Interface" is a documentation of the AT-Command set for devices which do not have an API-interface. To see whether the device is capable of receiving AT-Commands, please refer to table "Device Versions". If the device has been shipped with the API-Interface, please refer to the SW manual and "apiexample" code delivered with AX-SF-LIB-1-GEVK for an introduction on how to setup a project and how to use the API-Interface.

Serial Parameters: 9600, 8, N, 1

The AX-SFEU uses the UART (pins UARTTX, UARTRX) to communicate with a host and uses a bitrate of **9600 baud**, no parity, 8 data bits and one stop bit.

Power Modes



Standby

After Power-Up and after finishing a SIGFOX transmission, AX-SFEU enters Standby mode. In Standby mode, AX-SFEU listens on the UART for commands from the host. Also, OOB frames are transmitted whenever the OOB timer fires. To conserve power, the AX-SFEU can be put into Sleep or turned off (Deep Sleep) completely.

Sleep

The command AT\$P=1 is used to put the AX-SFEU into Sleep mode. In this mode, only the wakeup timer for out-of-band messages is still running. To wake the AX-SFEU up from Sleep mode toggle the serial UARTRX pin, e.g. by sending a break (break is an RS232 framing violation, i.e. at least 10 bit durations low). When an Out of Band (OOB) message is due, AX-SFEU automatically wakes up to transmit the message, and then returns to Sleep mode.

Deep Sleep

In Deep Sleep mode, the AX-SFEU is completely turned off and only draws negligible leakage current. Deep Sleep mode can be activated with AT\$P=2. To wake-up from Deep Sleep mode, GPIO9 is pulled to GND.

When using Deep Sleep mode, keep two things in mind: Everything is turned off, timers are not running at all and all settings will be lost (use **AT\$WR** to save settings to flash before entering Deep Sleep mode). Out-of-band messages will therefore not be sent. The pins states are frozen in Deep Sleep mode. The user must ensure that this will not result in condition which would draw a lot of current.

AT Commands

Numerical Syntax

```
hexdigit ::= [0-9A-Fa-f]
hexnum ::= "0x" hexdigit+
decnum ::= "0" | [1-9] [0-9]*
octnum ::= "0" [0-7]+
binnum ::= "0b" [01]+
bit ::= [01]
optnum ::= "-1"
```

frame ::= (hexdigit hexdigit)+

uint ::= hexnum | decnum | octnum | binnum

uint opt ::= uint | optnum

Command Syntax

A command starts with 'AT' (everything is case sensitive!), continues with the actual command followed by parameters (if any) and ends with any kind of whitespace (space, tab, newline etc.)

If incorrect syntax is detected ("parsing error") all input is ignored up until the next whitespace character.

Also note that any number can be entered in any format (Hexadecimal, Decimal, Octal and binary) by adding the corresponding prefix ('0x', none, '0', '0b'). The only exception is the 'Send Frame' command (AT\$SF) which expects a list of hexadecimal digits without any prefix.

Return Codes

A successful command execution is indicated by sending 'OK'. If a command returns a value (e.g. by querying a register) only the value is returned.

Examples

Bold text is sent to AX-SFEU.

AT\$SF=aabb1234

OK

Sends a Sigfox frame containing {0xaa : 0xbb : 0x12 : 0x34} without waiting for a response packet.

AT\$SF=0011223344,1

OK

RX=AA BB CC DD

Sends a Sigfox frame containing $\{0x00 : 0x11 : 0x22 : 0x33 : 0x44\}$ and waits for a response packet and outputs it on the UART.

AT\$CB=0xAA,1

OΚ

The 'CB' command sends out a continuous pattern of bits, in this case 0xAA = 0b10101010.

AT\$P=1

OK

This transitions the device into sleep mode. Out-of-band transmissions will still be triggered. The UART is powered

down. The device can be woken up by a low level on the UART signal, i.e. by sending break.

Table 10. COMMANDS

| Command | Name | Description | | | | | |
|----------------------------|-----------------------------------|---|--|---|--|--|--|
| AT | Dummy Command | Just returns 'OK' and does nothing else. Can be used to check communication. | | | | | |
| AT\$SB=bit[,bit] | Send Bit | Send a bit status (0 or 1). Optional bit flag indicates if AX-SFEU should receive a downlink frame. | | | | | |
| AT\$SF=frame[,bit] | Send Frame | Send payload data, 1 to 12 bytes. Optional bit flag indicates if AX-SFEU should receive a downlink frame. | | | | | |
| AT\$SO | Manually send out of band message | Send the out | Send the out-of-band message. | | | | |
| AT\$TR? | Get the transmit repeat | Returns the r | number of transm | nit repeats. Default: 2 | | | |
| AT\$TR=? | Get transmit repeat range | Returns the a | allowed range of | transmit repeats. | | | |
| AT\$TR=uint | Set transmit repeat | frame transm | ission with dowr | e: the TR value is effective only for nlink request (AT\$SF=payload,1). Uplink e transmit repeat = 2. | | | |
| ATSuint? | Get Register | Query a spec of registers. | cific configuration | register's value. See Table 11 for a list | | | |
| ATSuint=uint | Set Register | Change a co | nfiguration regist | ter. | | | |
| ATSuint=? | Get Register Range | Returns the r | ange of allowed | register values. | | | |
| AT\$IF=uint | Set TX Frequency | Set the output carrier macro channel for Sigfox frames. | | | | | |
| AT\$IF? | Get TX Frequency | Get the curre | Get the currently chosen TX frequency. | | | | |
| AT\$DR=uint | Set RX Frequency | Set the recep | Set the reception carrier macro channel for Sigfox frames. | | | | |
| AT\$DR? | Get RX Frequency | Get the currently chosen RX frequency. | | | | | |
| AT\$CW=uint,bit[,uint_opt] | Continuous Wave | To run emission tests for Sigfox certification it is necessary to send a continuous wave, i.e. just the base frequency without any modulation. Parameters: | | | | | |
| | | Name Range Description | | | | | |
| | | Frequency | 800000000- 999999999, 0 | Continuous wave frequency in Hz. Use 868130000 for Sigfox or 0 to keep previous frequency. | | | |
| | | Mode | 0, 1 | Enable or disable carrier wave. | | | |
| | | Power 0–14 dBm of signal Default: 14 Note: If the power parameter is omitted, then the default 14 i The value of register 302 has no effect on the AT\$CW mode | | | | | |
| AT\$CB=uint_opt,bit | Test Mode: TX constant byte | For emission testing it is useful to send a specific bit pattern. The first parameter specifies the byte to send. Use '-1' for a (pseudo-)random pattern. Parameters: | | | | | |
| | | Name | Range | Description | | | |
| | | Pattern | 0–255, –1 | Byte to send. Use '-1' for a (pseudo-)random pattern. | | | |
| | | Mode | 0, 1 | Enable or disable pattern test mode. | | | |
| AT\$T? | Get Temperature | Measure internal temperature and return it in 1/10 th of a degree Celsius. | | | | | |
| AT\$V? | Get Voltages | Return current voltage and voltage measured during the last transmission in mV. | | | | | |

Table 10. COMMANDS

| Command | Name | Description | | |
|------------|--------------------|--|--|--|
| AT\$I=uint | Information | Display various product information: 0: Software Name & Version Example Response: AX-SF 1.1-RC1 1: Contact Details Example Response: onhelp@onsemi.com 2: Silicon revision lower byte Example Response: 8F 3: Silicon revision upper byte Example Response: 00 4: Major Firmware Version Example Response: 1 5: Minor Firmware Version Example Response: 0 7: Firmware Variant (Frequency Band etc. (EU/US)) Example Response: RC1 8: Firmware VCS Version Example Response: 0 9: SIGFOX Library Version Example Response: UDL1-1.8.7 10: Device ID Example Response: 00012345 11: PAC Example Response: 0123456789ABCDEF | | |
| AT\$P=uint | Set Power Mode | To conserve power, the AX-SFEU can be put to sleep manually. Depending on power mode, you will be responsible for waking up the AX-SFEU again! 0: software reset (settings will be reset to values in flash) 1: sleep (send a break to wake up) 2: deep sleep (toggle GPIO9 or RESET_N pin to wake up; the AX-SFEU is not running and all settings will be reset!) | | |
| AT\$WR | Save Config | Write all settings to flash (RX/TX frequencies, registers) so they survive reset/deep sleep or loss of power. Use AT\$P=0 to reset the AX-SFEU and load settings from flash. | | |
| AT:Pn? | Get GPIO Pin | Return the setting of the GPIO Pin <i>n</i> ; <i>n</i> can range from 0 to 9. A character string is returned describing the mode of the pin, followed by the actual value. If the pin is configured as analog pin, then the voltage (range 01 V) is returned. The mode characters have the following meaning: Mode Description O Pin drives low 1 Pin drives high 2 Pin is high impedance input U Pin is input with pull-up A Pin is analog input (GPIO pin 03 only) T Pin is driven by clock or DAC (GPIO pin 0 and 4 only) The default mode after exiting reset is U on all GPIO pins. | | |
| AT:Pn=? | Get GPIO Pin Range | Print a list of possible modes for a pin. The table below lists the response. Pin Modes P0 0, 1, Z, U, A, T P1 0, 1, Z, U, A P2 0, 1, Z, U, A P3 0, 1, Z, U, A P4 0, 1, Z, U, T P5 0, 1, Z, U P6 0, 1, Z, U P7 0, 1, Z, U P8 0, 1, Z, U P9 0, 1, Z, U | | |
| AT:Pn=mode | Set GPIO Pin | Set the GPIO pin mode. For a list of the modes see the command AT:Pn? | | |

Table 10. COMMANDS

| Command | Name | Description | | | | |
|----------------------------|-----------------------------|---|--|--|--|--|
| AT:ADC Pn[-Pn [(1V 10V)]]? | Get GPIO Pin Analog Voltage | Measure the voltage applied to a GPIO pin. The command also allows measurement of the voltage difference across two GPIO pins. In differential mode, the full scale range may also be specified as 1 V or 10 V. Note however that the pin input voltages must not exceed the range 0VDD_IO. The command returns the result as fraction of the full scale range (1 V if none is specified). The GPIO pins referenced should be initialized to analog mode before issuing this command. | | | | |
| AT:SPI[(A B C D)]=bytes | SPI Transaction | This command clocks out <i>bytes</i> on the SPI port. The clock frequency is 312.5 kHz. The command returns the bytes read on MISO during output. Optionally the clocking mode may be specified (default is A): | | | | |
| | | Mode Clock Inversion Clock Phase | | | | |
| | | A normal normal B normal alternate C inverted normal D inverted alternate | | | | |
| | | SEL (GPIOx) MOSI D7 D6 D5 D4 D3 D2 D1 D0 MISO D7 D6 D5 D4 D3 D2 D1 D0 SCK B C D Note that SEL, if needed, is not generated by this command, and must instead be driven using standard GPIO commands (AT:Pn=0 1). | | | | |
| AT:CLK=freq,reffreq | Set Clock Generator | Output a square wave on the pin(s) set to T mode. The frequency of the square wave is (freq / 2^{16}) × reffreq. Possible values for reffreq are 20000000, 10000000, 5000000, 2500000, 1250000, 625000, 312500, 156250. Possible values for freq are 065535. | | | | |
| AT:CLK=OFF | Turn off Clock Generator | Switch off the clock generator | | | | |
| AT:CLK? | Get Clock Generator | Return the settings of the clock generator. Two numbers are returned, freq and reffreq. | | | | |
| AT:DAC=value | Set ΣΔ DAC | Output a $\Sigma\Delta$ DAC value on the pin(s) set to T mode. Parameter value may be in the range -3276832767 . The average output voltage is $(1/2 + \text{value} / 2^{17}) \times \text{VDD}$. An external low pass filter is needed to get smooth output voltages. The modulation frequency is 20 MHz. A possible low pass filter choice is a simple RC low pass filter with R = 10 k Ω and C = 1 μ F. | | | | |
| AT:DAC=OFF | Turn off ΣΔ DAC | Switch off the DAC | | | | |
| AT:DAC? | Get ΣΔ DAC | Return the DAC value | | | | |

Table 10. COMMANDS

| Command | Name | Description |
|--------------------------------|---|---|
| AT\$TM=mode,config | Activates the Sigfox Testmode | Available test modes: 0. TX BPSK Send only BPSK with Synchro Bit + Synchro frame + PN sequence: No hopping centered on the TX_frequency. Config bits 0 to 6 define the number of repetitions. Setting bit 7 to 1 removes the delay between frames. 1. TX Protocol: Tx mode with full protocol with Sigfox key: Send Sigfox protocol frames with initiate downlink flag = True. Config defines the number of repetitions. 2. RX Protocol: This mode tests the complete downlink protocol in Downlink only. Config defines the number of repetitions. 3. RX GFSK: RX mode with known pattern with SB + SF + Pattern on RX_frequency (internal comparison with received frame ⇔ known pattern = AA AA B2 27 1F 20 41 84 32 68 C5 BA AE 79 E7 F6 DD 9B. Config defines the RX on time in seconds. 4. RX Sensitivity: Does uplink + downlink frame with Sigfox key and specific timings. This test is specific to SIGFOX's test equipments & softwares. 5. TX Synthesis: Does one uplink frame on each Sigfox channel to measure frequency synthesis step. |
| AT\$PN=mode,rep (Note 3) | Send & Receive PN9 bitstream for BER measurements | Available modes: TX: 0, 1: start sending PN9 bit stream 0, 0: stop sending PN9 bit stream RX: 3, rep: 3 digits BER precision 4, rep: 4 digits BER precision 5, rep: 5 digits BER precision (slow!) Mode = 3–5 receive a PN9 bitstream and decodes it into a BER measurement. Reports BER on UART for each repetition.Rep is the number of measurements performed, valid range is 1–255. |
| AT\$SE | Starts AT\$TM=3,255 indefinitely | Convenience command for sensitivity tests |
| AT\$SL[=frame] | Send local loop | Sends a local loop frame with optional payload of 1 to 12 bytes. Default payload: 0x84, 0x32, 0x68, 0xC5, 0xBA, 0x53, 0xAE, 0x79, 0xE7, 0xF6, 0xDD, 0x9B. |
| AT\$RL | Receive local loop | Starts listening for a local loop. |
| AT\$TP=repetitions (Note 3) | Transient power measurement mode | Used for transmitter transient power measurements. The command switches the transmitter ON and OFF. During ON state (pseudo) random bit pattern is send. Repetitions is the number of performed measurements, acceptable range is 1–255. |

^{3.} This command is available only in AX–SFEU–1–03 and later.

Table 11. REGISTERS

| Number | Name | Description | Default | Range | Units |
|-----------------|--|--|---------|---------|--|
| 300 | Out Of Band Period | AX-SFEU sends periodic static messages to indicate that they are alive. Set to 0 to disable. | 24 | 0–24 | hours |
| 302 | Power Level | The output power of the radio. Note: This setting is used for all TX modes except AT\$CW. | 14 | 0–14 | dBm |
| 410 | Encryption Key Configuration | Set to zero for normal operation. Set to one for use with the SIGFOX Network Emulator Kit (SNEK) | 0 | 0–1 | 0: private key 1: public key |
| 411 (Note 4) | Enable Test Credentials for Sigfox Certification | Set to zero for use of regular device ID and key. Setting to one switches to test credentials for Sigfox Certification (Sigfox ID = 0xFEDCBA98. Key=0x0123456789ABCDEF012345 6789ABCDEF) | 0 | 0–1 | 0: regular ID and key 1: test credentials for Sigfox certification |
| 500 (Note 4) | RSSI Offset | RSSI offset value can be applied to fune tune the RSSI level that the deice reports | 0 | -128127 | dB |

^{4.} This register is only available only in AX-SFEU-1-03 and later.

APPLICATION INFORMATION

Typical Application Diagrams

Typical AX-SFEU / AX-SFEU-API Application Diagram

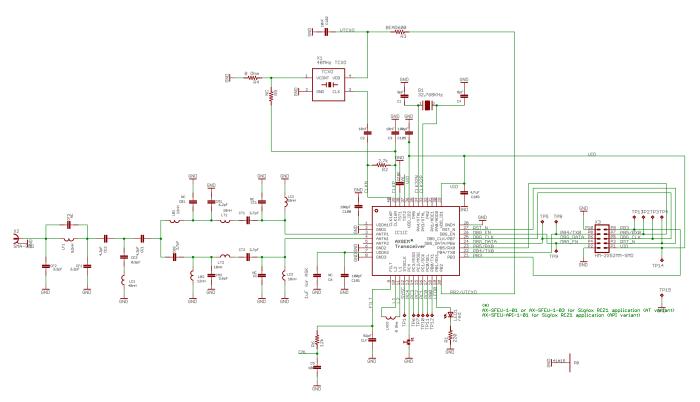


Figure 5. Typical Application Diagram

For detailed application configuration and BOM see the AX-SFEU Application Note: Sigfox Compliant Reference Design.

QFN40 PACKAGE INFORMATION

QFN40 Soldering Profile

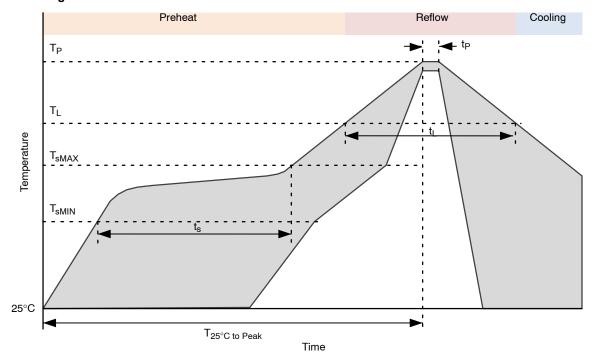


Figure 6. QFN40 Soldering Profile

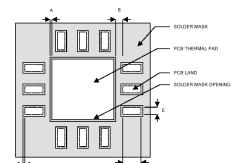
Table 12.

| Profile Feature | Pb-Free Process | |
|--|---------------------------|--------------|
| Average Ramp-Up Rate | | 3°C/s max. |
| Preheat Preheat | | |
| Temperature Min | T_{sMIN} | 150°C |
| Temperature Max | T_{sMAX} | 200°C |
| Time (T _{sMIN} to T _{sMAX}) | t _s | 60 – 180 sec |
| Time 25°C to Peak Temperature | T _{25°C to Peak} | 8 min max. |
| Reflow Phase | | |
| Liquidus Temperature | T_L | 217°C |
| Time over Liquidus Temperature | t_L | 60 – 150 s |
| Peak Temperature | t _p | 260°C |
| Time within 5°C of actual Peak Temperature | T_p | 20 – 40 s |
| Cooling Phase | | |
| Ramp-down rate | | 6°C/s max. |

^{5.} All temperatures refer to the top side of the package, measured on the package body surface.

QFN40 Recommended Pad Layout

1. PCB land and solder masking recommendations are shown in Figure 7.



- A = Clearance from PCB thermal pad to solder mask opening, 0.0635 mm minimum
- B = Clearance from edge of PCB thermal pad to PCB land, 0.2 mm minimum
- C = Clearance from PCB land edge to solder mask opening to be as tight as possible to ensure that some solder mask remains between PCB pads.
- D = PCB land length = QFN solder pad length + 0.1 mm
- E = PCB land width = QFN solder pad width + 0.1 mm

Figure 7. PCB Land and Solder Mask Recommendations

- 2. Thermal vias should be used on the PCB thermal pad (middle ground pad) to improve thermal conductivity from the device to a copper ground plane area on the reverse side of the printed circuit board. The number of vias depends on the package thermal requirements, as determined by thermal simulation or actual testing.
- 3. Increasing the number of vias through the printed circuit board will improve the thermal conductivity to the reverse side ground plane and external heat sink. In general, adding more metal through the PC board under the IC will improve operational heat transfer, but will require careful attention to uniform heating of the board during assembly.

Assembly Process

Stencil Design & Solder Paste Application

- 1. Stainless steel stencils are recommended for solder paste application.
- 2. A stencil thickness of 0.125 0.150 mm (5 6 mils) is recommended for screening.

- 3. For the PCB thermal pad, solder paste should be printed on the PCB by designing a stencil with an array of smaller openings that sum to 50% of the QFN exposed pad area. Solder paste should be applied through an array of squares (or circles) as shown in Figure 8.
- 4. The aperture opening for the signal pads should be between 50–80% of the QFN pad area as shown in Figure 9.
- 5. Optionally, for better solder paste release, the aperture walls should be trapezoidal and the corners rounded.
- 6. The fine pitch of the IC leads requires accurate alignment of the stencil and the printed circuit board. The stencil and printed circuit assembly should be aligned to within + 1 mil prior to application of the solder paste.
- 7. No-clean flux is recommended since flux from underneath the thermal pad will be difficult to clean if water-soluble flux is used.

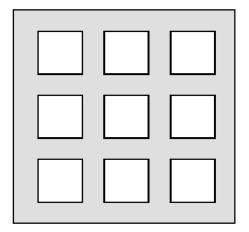


Figure 8. Solder Paste Application on Exposed Pad

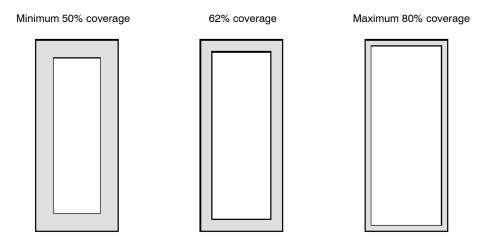


Figure 9. Solder Paste Application on Pins

Life Support Applications

This product is not designed for use in life support appliances, devices, or in systems where malfunction of this product can reasonably be expected to result in personal injury. ON Semiconductor customers using or selling this product for use in such applications do so at their own risk

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Device Information

The following device information can be queried using the AT-Commands AT\$I=4, AT\$I=5 for the APP version and AT\$I=2, AT\$I=3 for the chip version.

Table 13. DEVICE VERSIONS

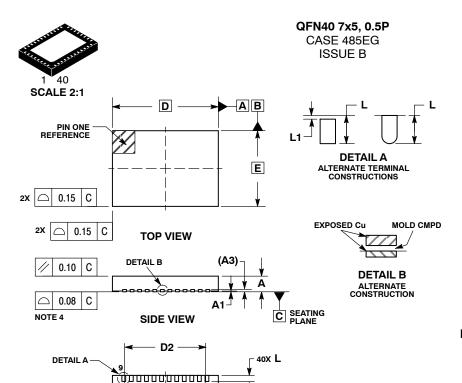
| | | | Firmware Version | | Silicon Version | |
|--------------|-----------------------|--------------|------------------|-------|-----------------|------------|
| Product | Part Number | Marking | Major | Minor | Lower Byte | Upper Byte |
| AX-SFEU | AX-SFEU-1-01-XXXX | AX8052F143-2 | 0x01 | 0x01 | 0x8F | 0x51 |
| | (Note 6) | SFEU-101 | 0x01 | 0x01 | 0x90 | 0x51 |
| | AX-SFEU-1-03-TX30 | SFEU-103 | 0x01 | 0x01 | 0x90 | 0x51 |
| AX-SFEU-API | AX-SFEU-API-1-01-XXXX | AX8052F143-2 | - | - | 0x8F | 0x51 |
| (Notes 6, 7) | (Notes 6, 7) | SFEU-API-101 | - | - | 0x90 | 0x51 |

^{6.} TB05 for Reel 500, TX30 for Reel 3000.

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^{7.} Updated AX-SF-LIB-1-GEVK library for AX-SFEU-API can be retrieved from ON Semiconductor website.

E2



0.10 C A B

C NOTE 3

0.05

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DATE 26 APR 2017

NOTES:

- NOTES:

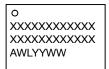
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSIONS: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| | MILLIMETERS | | | | | |
|-----|-------------|----------|--|--|--|--|
| DIM | MIN | MAX | | | | |
| Α | 0.80 | 1.00 | | | | |
| A1 | 0.00 | 0.05 | | | | |
| A3 | 0.20 | REF | | | | |
| b | 0.18 | 0.30 | | | | |
| D | 7.00 | 7.00 BSC | | | | |
| D2 | 5.30 | 5.50 | | | | |
| E | 5.00 | BSC | | | | |
| E2 | 3.30 | 3.50 | | | | |
| е | 0.50 BSC | | | | | |
| L | 0.30 | 0.50 | | | | |
| L1 | | 0.15 | | | | |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

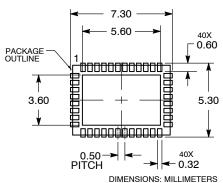
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*

BOTTOM VIEW

е

e/2



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| DESCRIPTION: | QFN40 7X5, 0.5P | | PAGE 1 OF 1 | | |

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EC25AUTFA-MINIPCIE EC25AFFA-MINIPCIE EP06ALA-512-SGAD EM06ALA-512-SGAD EM12GPA-512-SGAD EC25EUGA
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AWR1642ABIGABLQ1 ESP32-D0WD ESP8266EX CYBL10561-56LQXI ATWINC1500B-MU-Y DA14531-00000FX2 ESP32-C3FH4

ESP32-C3 ESP32-D0WDQ6 ESP32-D0WDQ6-V3 ESP32-D0WD-V3 ESP32-PICO-V3 ESP32-PICO-V3-02 ESP32-S2